



Features

- 0805 size
- Available in E12 series
- High Q up to 80 typ.
- High operating temperature of 125 °C
- Small size of only 2.0 mm
- Lead Free

Applications

- Mobil phones
- Cellular phones
- CTV, VCR, HIC, FDD

BOURNS®

CW201212 Series - High Q Chip Inductors

Electrical Specifications

Bourns Part No.	Inductance		Q	Test Freq. MHz		SRF min.	RDC	I rms
	nH	Tol. %	min.	L	Q	MHz	ohms	mA max.
CW201212-2N2J	2.2	±5	50	250	1000	6000	0.06	600
CW201212-2N7J	2.7	±5	35	250	1000	6000	0.08	600
CW201212-2N8J	2.8	±5	32	250	1000	6000	0.06	800
CW201212-3N3J	3.3	±5	30	250	1500	6000	0.08	600
CW201212-3N9J	3.9	±5	60	250	1000	6000	0.06	600
CW201212-4N7J	4.7	±5	60	250	1000	5800	0.06	600
CW201212-5N6J	5.6	±5	60	250	1000	5800	0.08	600
CW201212-6N8J	6.8	±5	60	250	1000	5800	0.06	600
CW201212-8N2J	8.2	±5	60	250	1000	5500	0.06	600
CW201212-10NJ	10	±5	60	250	500	4800	0.08	600
CW201212-12NJ	12	±5	60	250	500	4100	0.08	600
CW201212-15NJ	15	±5	60	250	500	3600	0.08	600
CW201212-18NJ	18	±5	60	250	500	3400	0.08	600
CW201212-22NJ	22	±5	60	250	500	3300	0.10	600
CW201212-27NJ	27	±5	60	250	500	2600	0.12	600
CW201212-33NJ	33	±5	60	250	500	2400	0.15	500
CW201212-39NJ	39	±5	60	250	500	2100	0.18	500
CW201212-47NJ	47	±5	60	200	500	1700	0.15	500
CW201212-56NJ	56	±5	60	200	500	1600	0.25	500
CW201212-68NJ	68	±5	60	200	500	1450	0.27	500
CW201212-82NJ	82	±5	60	150	500	1350	0.32	500
CW201212-R10J	100	±5	60	150	500	1200	0.43	400
CW201212-R12J	120	±5	50	150	250	1100	0.48	400
CW201212-R15J	150	±5	50	100	250	950	0.67	400
CW201212-R18J	180	±5	50	100	250	900	0.85	350
CW201212-R22J	220	±5	50	100	250	860	1.10	300
CW201212-R27J	270	±5	45	100	250	850	1.46	250
CW201212-R33J	330	±5	45	100	250	800	1.65	200
CW201212-R39J	390	±5	45	100	250	780	2.20	170
CW201212-R47J	470	±5	33	250	100	375	1.72	250
CW201212-R56J	560	±5	23	50	50	340	1.90	230
CW201212-R68J	680	±5	23	25	50	270	2.05	190
CW201212-R82J	820	±5	23	25	50	230	2.30	180
CW201212-R91J	910	±5	22	22	50	220	2.50	150

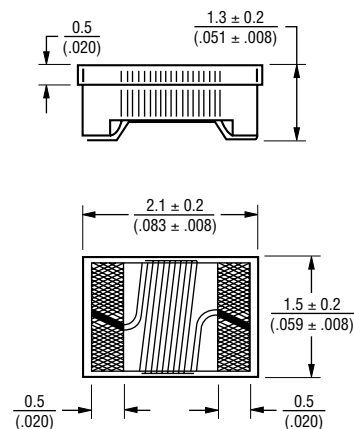
General Specifications

Temperature Rise
40 °C max. at rated current
 Operating Temperature
-40 °C to +125 °C
 Storage Temperature...-40 °C to +125 °C
 Reflow Soldering ...230 °C, 50 sec. max.
 Resistance to Soldering Heat
260 °C, 5 seconds

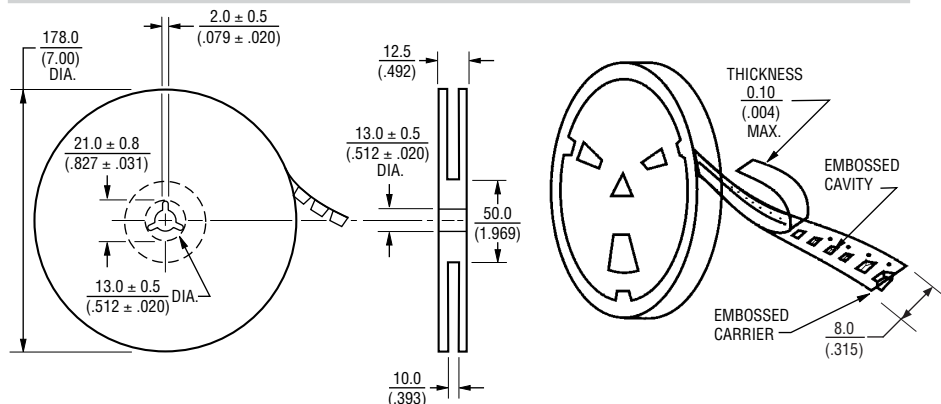
Materials

Core Material
 -2N2J through -R39JCeramic
 -R47J through -R91JFerrite
 WireEnamelled Copper (1W1E180)
 Terminal.....Mo/Mn+Ni+Au
 Packaging.....2,000 pcs. per reel

Product Dimensions

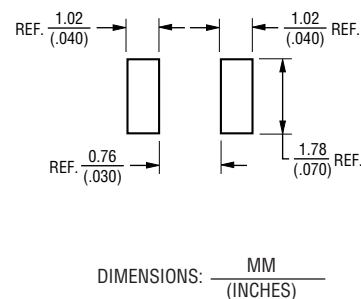


Packaging Specifications



NOTE: 2% TOLERANCE AVAILABLE FOR INDUCTANCE RANGES OF 12 NH AND UP. REPLACE "J" WITH "G".

Recommended Layout



REV. 09/09

*RoHS Directive 2002/95/EC Jan 27 2003 including Annex Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.